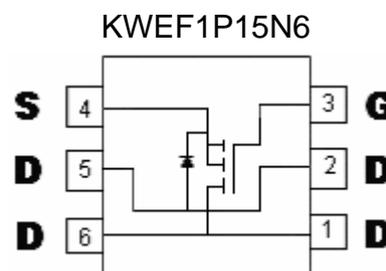


## P-Channel Enhancement Mode Power MOSFET

### Features:

- Simple drive requirement
- Low on-resistance
- Small package outline
- Pb-free lead plating package

### Equivalent Circuit



G : Gate S : Source D : Drain

### Description:

The KWEF1P15N6 is a P-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The SOT-26 package is universally preferred for all commercial-industrial surface mount applications.

### Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V <sub>DS</sub>	-150	V
Gate-Source Voltage		V <sub>GS</sub>	±20	
Continuous Drain Current	T <sub>C</sub> =25 °C	I <sub>D</sub>	-1.4	A
	T <sub>C</sub> =70 °C		-1.1	
	T <sub>A</sub> =25 °C (Note 1)		-1.1	
	T <sub>A</sub> =70 °C (Note 1)		-0.88	
Pulsed Drain Current (Note 2, 3)		I <sub>DM</sub>	-5.6	
Total Power Dissipation	T <sub>C</sub> =25 °C	P <sub>D</sub>	3.2	W
	T <sub>C</sub> =70 °C		2.1	
	T <sub>A</sub> =25 °C		2	
	T <sub>A</sub> =70 °C		1.25	
Operating Junction Temperature and Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55~+150	°C

## Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	39	°C/W
Thermal Resistance, Junction-to-ambient, max (Note 1)	$R_{\theta JA}$	62.5	

Note : 1.Surface mounted on 1 in<sup>2</sup> copper pad of FR-4 board,  $t \leq 5$  sec. 156°C/W when mounted on minimum copper pad.  
 2.Pulse width limited by maximum junction temperature.  
 3.Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

## Electrical Characteristics (Ta=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
$BV_{DSS}$	-150	-	-	V	$V_{GS}=0, I_D=-250\mu A$
$\Delta BV_{DSS}/\Delta T_j$	-	-0.1	-	V/°C	Reference to 25°C, $I_D=-250\mu A$
$V_{GS(th)}$	-2	-2.8	-3.5	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20V, V_{DS}=0$
$I_{DSS}$	-	-	-100		$V_{DS}=-120V, V_{GS}=0, T_j=25^\circ C$
	-	-	-10	$\mu A$	$V_{DS}=-120V, V_{GS}=0, T_j=55^\circ C$
* $R_{DS(ON)}$	-	661	820	mΩ	$I_D=-1.4A, V_{GS}=-10V$
	-	724	850		$I_D=-1A, V_{GS}=-6V$
* $G_{FS}$	-	2.5	-	S	$V_{DS}=-10V, I_D=-1.4A$
<b>Dynamic</b>					
$C_{iss}$	-	471	-	pF	$V_{DS}=-30V, V_{GS}=0, f=1MHz$
$C_{oss}$	-	28	-		
$C_{rSS}$	-	11	-		
$t_{d(ON)}$	-	8	-	ns	$V_{DS}=-75V, I_D=-1A, V_{GS}=-10V, R_G=1\Omega$
$t_r$	-	6	-		
$t_{d(OFF)}$	-	20	-		
$t_f$	-	4	-		
$Q_g$	-	6	-	nC	$V_{DS}=-75V, I_D=-1A, V_{GS}=-10V,$
$Q_{gs}$	-	2	-		
$Q_{gd}$	-	1.4	-		
<b>Source-Drain Diode</b>					
* $I_S$	-	-	-1.4	A	
* $I_{SM}$	-	-	-5		
* $V_{SD}$	-	-0.77	-1.2	V	$I_S=-1A, V_{GS}=0V$
* $T_{rr}$	-	60	-	ns	$I_S=-1A, V_{GS}=0V, dI/dt=100A/\mu s$
$Q_{rr}$	-	120	-	nC	

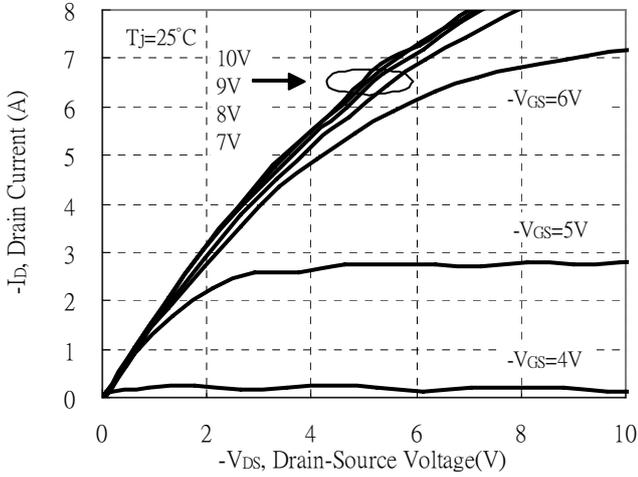
\*Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

## Ordering Information

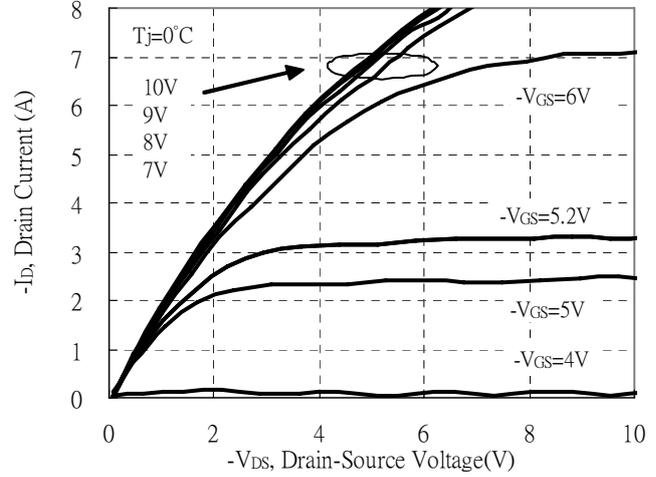
Device	Package	Shipping
KWEF1P15N6	SOT-26 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

**Typical Characteristics**

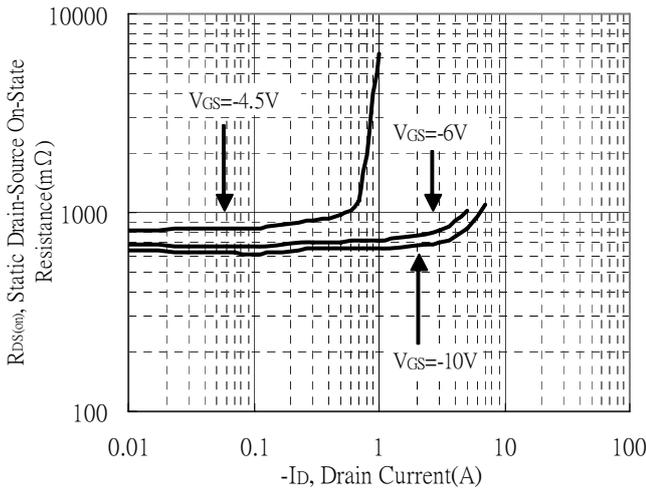
Typical Output Characteristics



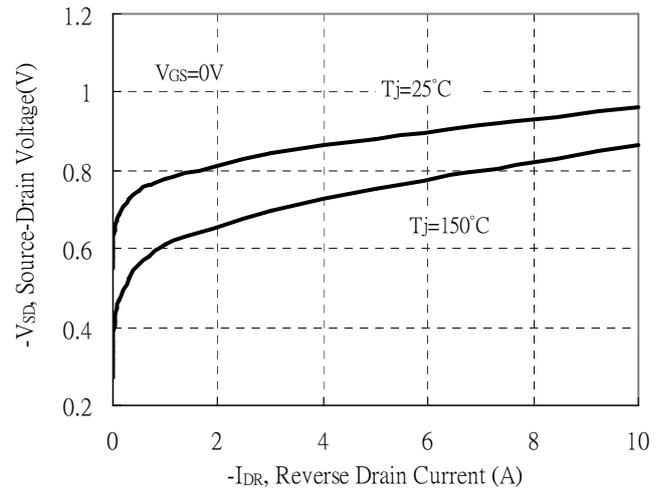
Typical Output Characteristics



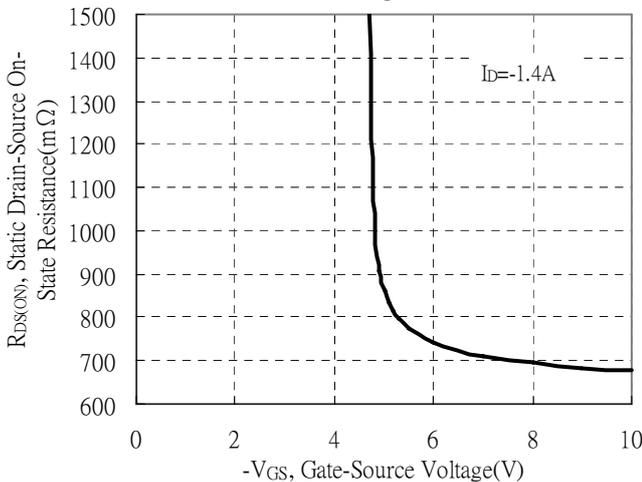
Static Drain-Source On-State resistance vs Drain Current



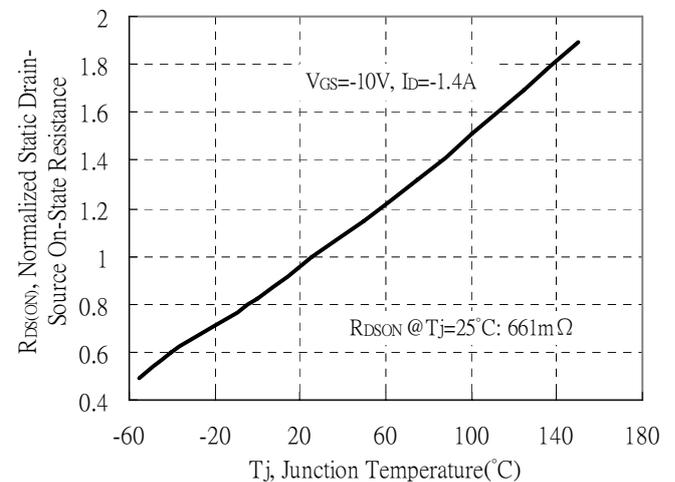
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

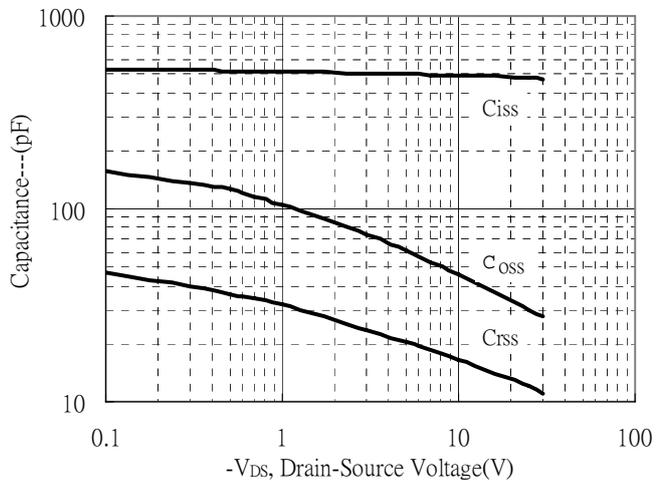


Drain-Source On-State Resistance vs Junction Temperature

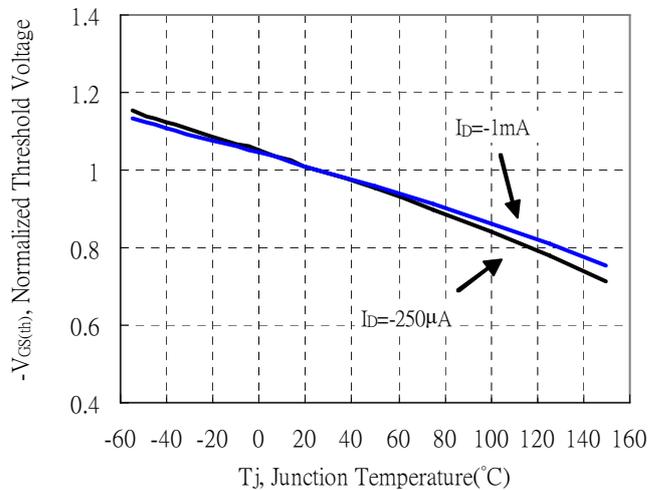


**Typical Characteristics(Cont.)**

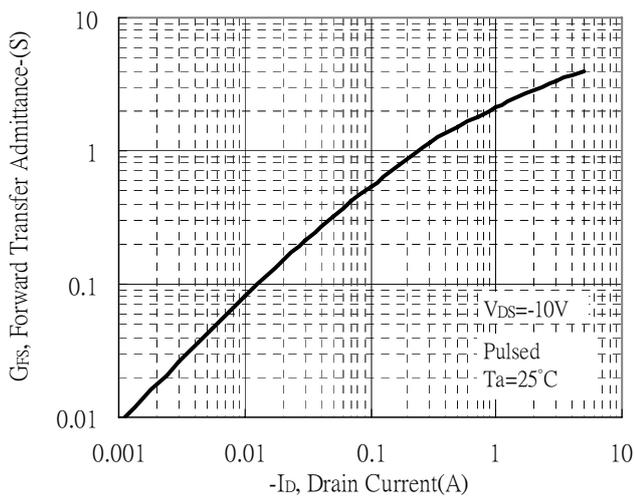
Capacitance vs Drain-to-Source Voltage



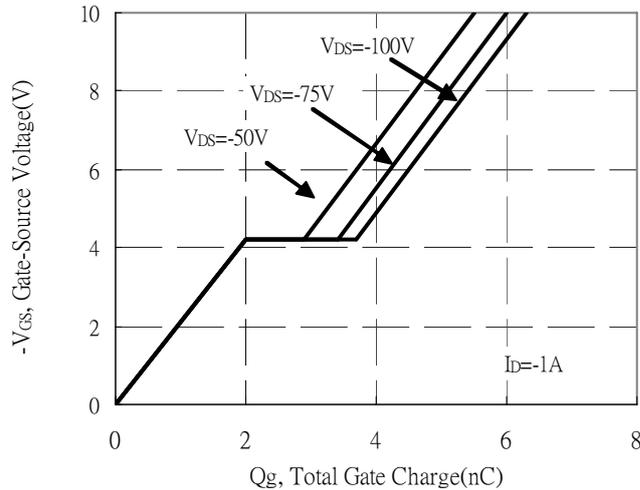
Threshold Voltage vs Junction Temperature



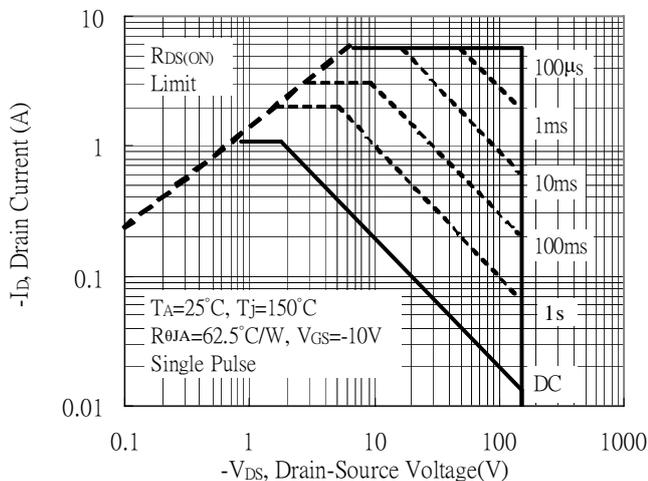
Forward Transfer Admittance vs Drain Current



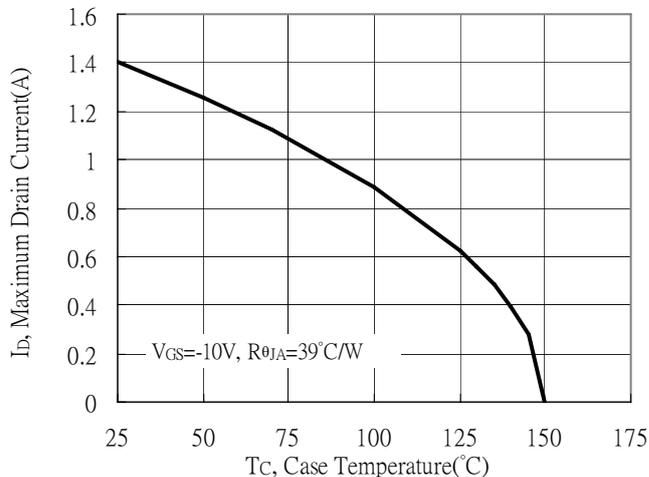
Gate Charge Characteristics



Maximum Safe Operating Area

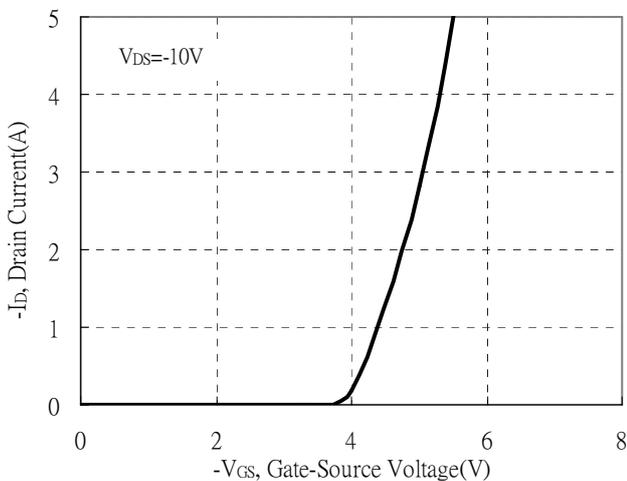


Maximum Drain Current vs Case Temperature

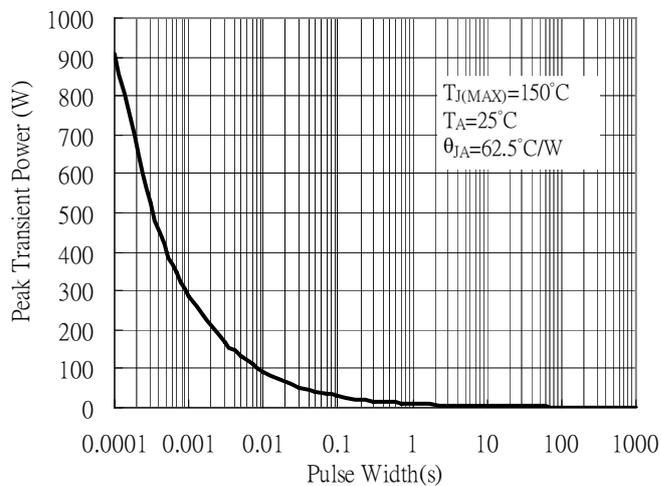


**Typical Characteristics(Cont.)**

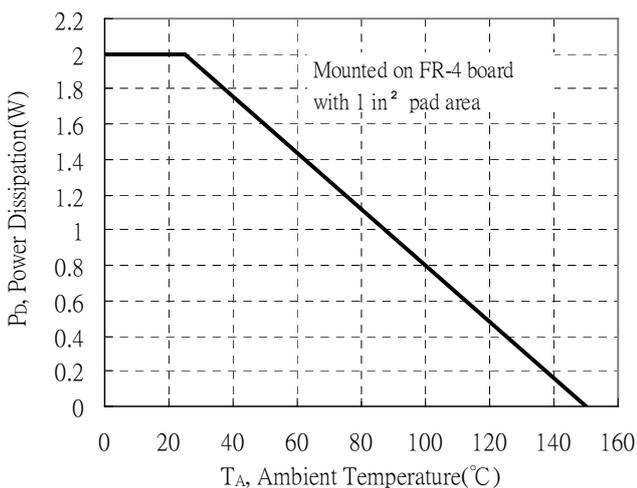
Typical Transfer Characteristics



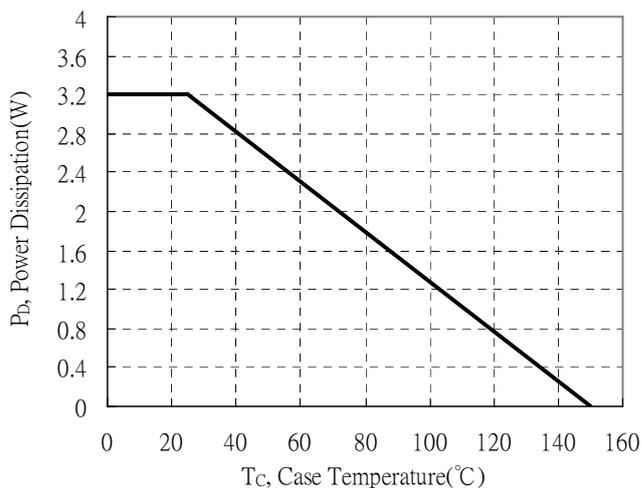
Single Pulse Maximum Power Dissipation



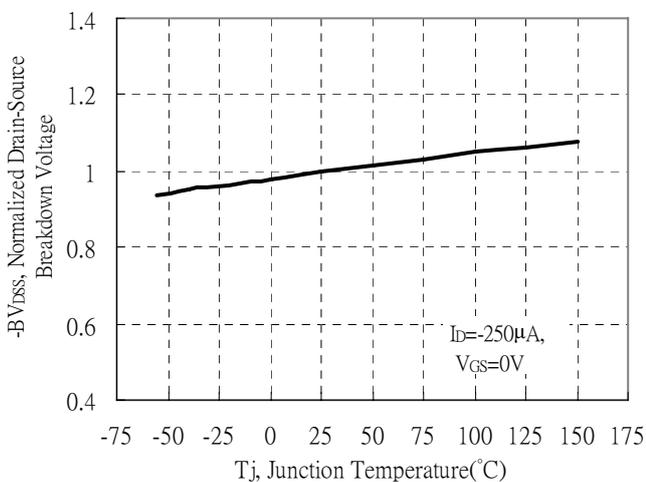
Power Derating Curve



Power Derating Curve

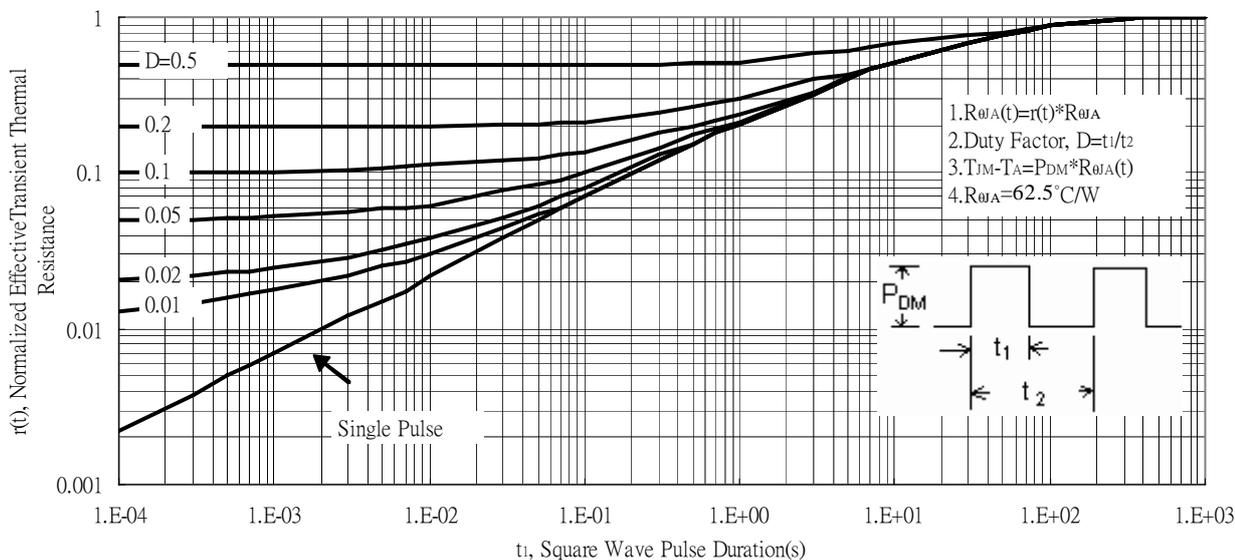


Breakdown Voltage vs Ambient Temperature

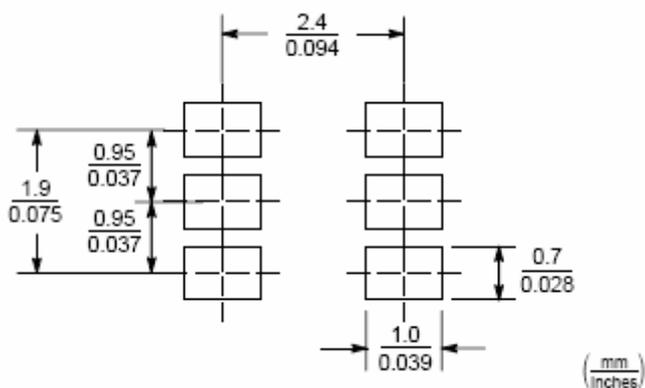


### Typical Characteristics(Cont.)

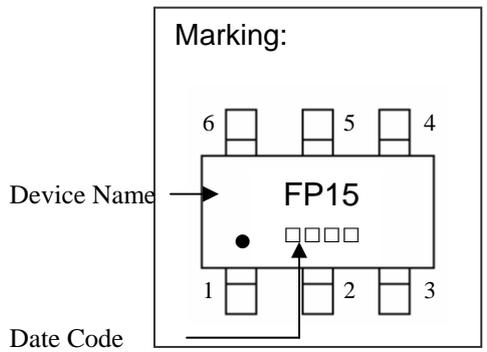
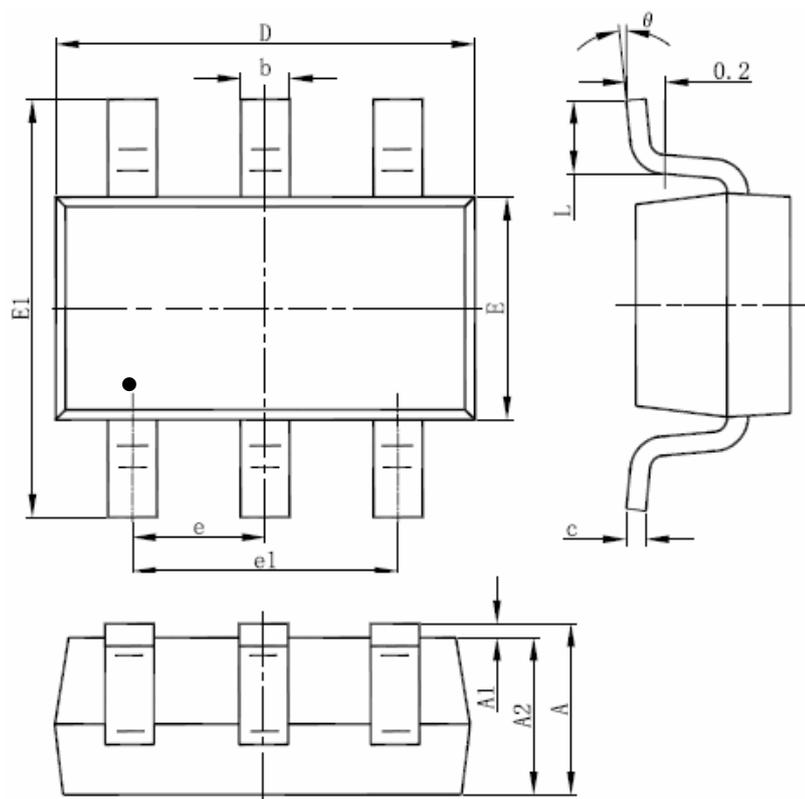
Transient Thermal Response Curves



### Recommended Soldering Footprint



**SOT-26 Dimension**



6-Lead SOT-26 Plastic Surface Mounted Package Code: N6

- Style:
- Pin 1. Drain (D)
  - Pin 2. Drain (D)
  - Pin 3. Gate (G)
  - Pin 4. Source (S)
  - Pin 5. Drain (D)
  - Pin 6. Drain (D)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049	E	1.500	1.700	0.059	0.067
A1	0.000	0.100	0.000	0.004	E1	2.650	2.950	0.104	0.116
A2	1.050	1.150	0.041	0.045	e	0.950 (BSC)		0.037 (BSC)	
b	0.300	0.500	0.012	0.020	e1	1.800	2.000	0.071	0.079
c	0.100	0.200	0.004	0.008	L	0.300	0.600	0.012	0.024
D	2.820	3.020	0.111	0.119	θ	0°	8°	0°	8°